



100% Material Declaration Data Sheet TQ144

PK169 (v1.2) October 3, 2006

Material Declaration Data Sheet

Average Weight: 1.28 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.01344	1.05 %
	Silicon	7440-21-3	100.00		0.01344	
Die Attach					0.002048	0.16 %
	Silver	7440-22-4	78.00		0.00159744	
	Epoxy (EP)	Trade Secret	22.00		0.00045056	
Mold Compound					1.007616	78.72 %
	Epoxy Resin (EP)	Trade Secret	9.00		0.09068544	
	Phenolic Resin	Trade Secret	7.00	Resin	0.07053312	
	Carbon Black	1333-86-4	0.50		0.00503808	
	Silica	60676-86-0	82.50		0.8312832	
	Bismuth	7440-69-9	Max. 1.00%		0.01007616	
Leadframe					0.238848	18.66 %
	Copper	7440-50-8	98.85		0.236101248	
	Chromium	7440-47-3	0.30		0.000716544	
	Tin	7440-31-5	0.25		0.00059712	
	Zinc	7440-66-6	0.60		0.001433088	
Leadframe Plating					0.001024	0.08%
	Silver	7440-22-4	100.00		0.001024	
Bond Wire					0.005632	0.44 %
	Gold	7440-57-5	100.00		0.005632	
External Plating					0.011392	0.89 %
	Tin	7440-31-5	85.00		0.0096832	
	Lead	7439-92-1	15.00		0.0017088	

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Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/16/06	1.0	Initial release.
7/05/06	1.1	100% Material Declaration.
10/3/06	1.2	Updated component descriptions.